

Patent Abstracts of Japan

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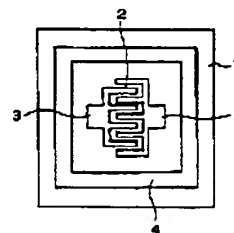
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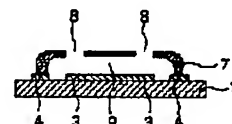
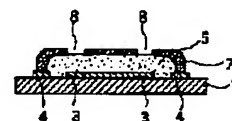
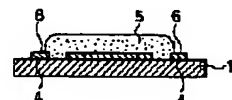
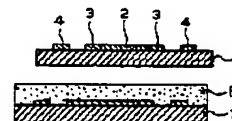
APPLICANT : KOKUSAI ELECTRIC CO LTD;

INVENTOR : YAMASUMI NAOYA;

INT.CL. : H03H 3/08 H03H 9/25

TITLE : SURFACE ACOUSTIC WAVE DEVICE
AND MANUFACTURE OF THE SAME

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ABSTRACT : PROBLEM TO BE SOLVED: To remove the limit of miniaturization owing to the package of a surface acoustic wave device and to reduce the cost.

SOLUTION: An IDT (reed screen-like interdigital electrode) 2 and enveloping electrodes 4 surrounding a surface acoustic wave exciting part by means of IDT are simultaneously formed on a wafer-like piezoelectric substrate 1. A sacrifice layer 5 and a resin layer 7 of silicon oxide and the like are stacked and formed on the whole surface of a wafer. Window holes 8 having the same areas as the terminal electrodes 3 are provided in positions corresponding to the terminal electrodes 3 of IDT. A hollow part 9 is formed at the inner side of the enveloping electrodes 4 and the resin layer 7 by immersing them in buffered hydrofluoric acid and eluding the sacrifice layer 5 from the window holes 8.

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